

FORM PTO-1390 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

TRANSMITTAL LETTER TO THE UNITED STATES DESIGNATED/ELECTED OFFICE (DO/EO/US) CONCERNING A FILING UNDER 35 U.S.C. 371

ATTORNEY'S DOCKET NO.
PHN 17,557

U.S. Application No. (if known, see 37 CFR 1.5)

09/787838

INTERNATIONAL APPLICATION NO.
PCT/EP00/06817

INTERNATIONAL FILING DATE
JULY 17, 2000

PRIORITY DATE CLAIMED
JULY 22, 1999

TITLE OF INVENTION
METHOD OF MANUFACTURING A MAGNETIC TUNNEL JUNCTION DEVICE

APPLICANT(S) FOR DO/EO/US
JOANNES BAD VAN ZON

Applicant(s) herewith submit to the United States Designated/Elected Office (DO/EO/US) the following items and other information:

1. ☒ This is a FIRST submission of items concerning a filing under 35 U.S.C. 371.
 2. ☐ This is a SECOND or SUBSEQUENT submission of items concerning a filing under 35 U.S.C. 371.
 3. ☐ This express request to begin national examination procedures (35 U.S.C. 371(f)) at any time rather than delay examination until the expiration of the applicable time limit set in 35 U.S.C. 371(b) and PCT Articles 22 and 39(1).
 4. ☐ A proper Demand for International Preliminary Examination was made by the 19th month from the earliest claimed priority date.
 5. ☒ A copy of the International Application as filed (35 U.S.C. 371 (c)(2))
 - a. ☒ is transmitted herewith (required only if not transmitted by the International Bureau).
 - b. ☐ has been transmitted by the International Bureau.
 - c. ☐ is not required, as the application was filed in the United States Receiving Office (RO/US).
 6. ☐ A translation of the International Application into English (35 U.S.C. 371(c)(2))
 7. ☐ Amendments to the claims of the International Application under PCT Article 19 (35 U.S.C. 371(c)(3))
 - a. ☐ are transmitted herewith (required only if not transmitted by the International Bureau).
 - b. ☐ have been transmitted by the International Bureau.
 - c. ☐ have not been made; however, the time limit for making such amendments has NOT expired.
 - d. ☐ have not been made and will not be made.
 8. ☐ A translation of the amendment to the claims under PCT Article 19 (35 U.S.C. 371 (c)(3)).
 9. ☒ An oath or declaration of the inventor(s) (35 U.S.C. 371(c)(4)).
 10. ☐ A translation of the annexes to the International Preliminary Examination Report under PCT Article 36 (35 U.S.C. 371(c)(5)).
- Items 11. to 16. Below concern document(s) or information included:
11. ☒ An Information Disclosure Statement under 37 C.F.R. 1.97 and 1.98.
 12. ☐ An assignment document for recording. A separate cover sheet in compliance with 37 C.F.R. 3.28 and 3.31 is included.
 13. ☒ A FIRST preliminary amendment.
☐ A SECOND OR SUBSEQUENT preliminary amendment.
 14. ☐ A substitute specification.
 15. ☒ A change of power of attorney and/or address letter.
 16. ☒ Other items or information:
2 SHEETS OF DRAWING
CHARGE AUTHORIZATION

CERTIFICATE OF EXPRESS MAILING

Express Mail Mailing Label No. EL 686949082
Date of Deposit March 22, 2001

I hereby certify that this paper and/or fee is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 C.F.R. 1.10 on the date indicated above and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

Valerie Deas
Typed Name Signature

U.S. APPLICATION NO. (If known, see 37 C.F.R. 1.5)

INTERNATIONAL APPLICATION NO.

ATTORNEY'S DOCKET NUMBER

PCT/EP00/06817

PHN 17,557

09/787838

17 [] The following fees are submitted:

BASIC NATIONAL FEE (37 C.F.R. 1.492(A)(1)-(5)):

Search Report has been prepared by the EPO or JPO

00

\$940.

International preliminary-examination fee paid to USPTO
(37 C.F.R. 1.482)

00

\$720.

No international preliminary examination fee paid to USPTO
(37 C.F.R. 1.482) but international search fee paid to USPTO
(37 C.F.R. 1.445(a)(2))

\$760.00

\$970.00

Neither international preliminary examination fee (37 C.F.R.
1.482) nor international search fee (37 C.F.R. 1.445(a)(2))
paid to USPTO

00

\$970.

International preliminary examination fee paid to USPTO
(37 C.F.R. 1.482) and all claims satisfied provisions of PCT
Article 33(2)-(4)

96.00

\$

ENTER APPROPRIATE BASIC FEE AMOUNT =

Surcharge of \$130.00 for furnishing the oath or declaration later than [] 20 [] 30
months from the earliest claimed priority date (37 C.F.R. 1.492(e)).

\$

CLAIMS	NUMBER FILED	NUMBER EXTRA	RATE		
Total Claims	9 - 20 =	0	X \$ 18.00	\$	
Independent claims	1 - 3 =	0	X \$ 78.00	\$	
MULTIPLE DEPENDENT CLAIMS (if applicable)			+ \$260.00	\$	
TOTAL OF ABOVE CALCULATIONS =				\$970.00	
Reductions by 1/2 for filing by small entity, if applicable. Verified Small Entity Statement must also be filed (Note 37 C.F.R. 1.9, 1.27, 1.28)				\$	
SUBTOTAL =				\$970.00	
Processing fee of \$130.00 for furnishing the English translation later than [] 20 [] 30 months from the earliest claimed priority date (37 C.F.R. 1.492(f)).				\$	
TOTAL NATIONAL FEE =				\$	
Fee for recording the enclosed assignment (37 C.F.R. 1.21(h)). The assignment must be accompanied by an appropriate cover sheet (37 C.F.R. 3.28, 3.31). \$40.00 per property				\$40.00	
TOTAL FEES ENCLOSED =				\$1010.00	
				Amount to be Refunded	\$
				Charged	\$

a. [] A check in the amount \$_____ to cover the above fees is enclosed.

b. [X] Please charge my Deposit Account No. 14-1270 in the amount of \$1,010.00 to cover the above fees.
A duplicate copy of this sheet is enclosed.c. [X] The Commissioner is hereby authorized to charge any additional fee, with the exception of the Base Issue Fee, which may be required, or credit any overpayment to Deposit Account No. 14-1270. A duplicate copy of this sheet is enclosed.

NOTE: Where an appropriate time limit under 37 C.F.R. 1.494 or 1.495 has not been met, a petition to revive (37 C.F.R. 1.137(a) or (b)) must be filed and granted to restore the application to pending status.

SEND ALL CORRESPONDENCE TO:

(SIGNATURE)

Corporate Patent Counsel
Philips Electronics North America Corporation
80 White Plains Road
Tarrytown, NY 10591MICHAEL E. MARION
(NAME)32,266
(REGISTRATION NUMBER)

Method of manufacturing a magnetic tunnel junction device.

The invention relates to a method of manufacturing a magnetic tunnel junction device, in which a stack comprising two electrode layers, comprising a magnetic material, and a barrier layer extending in between, comprising a non-magnetic material, is formed.

The invention also relates to a magnetic tunnel junction device obtainable by means of such a method, a magnetic field sensor provided with such a device and a magnetic memory provided with such a device.

A device as described above is disclosed in WO-A 99/22368. The magnetic tunnel junction device known from said patent application comprises a first and a second magnetic layer, which layers are sandwiched with respect to an insulating intermediate layer and serve as electrode layers. As a transducing element, this device forms part of a magnetic field sensor provided with a magnetic yoke, in which the first magnetic layer is in direct contact with a part of the yoke. The first magnetic layer, likewise as the yoke, is formed from a soft-magnetic material. The second magnetic layer is a composite layer and comprises a ferromagnetic sub-layer and a pinning structure. The insulating intermediate layer constitutes a tunnel barrier.

In the known magnetic tunnel junction device, one of the magnetic layers, namely the soft-magnetic layer, therefore also serves as a flux guide. To prevent detrimental effects on the magnetical properties of this layer, such as domain wall formation due to irregularities in the surface of the soft-magnetic layer facing the tunnel barrier, it is desirable that only the other magnetic layer, i.e. the second magnetic layer, and possibly the barrier-forming intermediate layer, is, or are, structured.

It is an object of the invention to provide a method of the type described in the opening paragraph, comprising a process of structuring one of the electrode layers, which process stops with certainty before the other electrode layer is reached.

To achieve the object described, the method according to the invention is characterized in that one of the electrode layers is structured by means of etching, in which, during etching, a part of the relevant layer is made thinner by removing material until a rest layer remains, whereafter this rest layer is removed by means of physical etching, in which at

least substantially particles have a motion energy which is between the sputtering threshold of the magnetic material of the rest layer and the sputtering threshold of the non-magnetic material of the barrier layer. Physical etching is understood to mean etching by means of a beam of electrically charged particles, such as sputter etching, ion milling and ion beam etching. As is assumed to be known, the sputtering threshold is the minimal energy which is necessary to release a particle from the material of the layer which is subjected to an etching process.

In the method according to the invention, it is with certainty that the other electrode layer is not reached because the electrode layer to be structured is not entirely etched off during a first phase of the etching process in which use is made in known manner of a mask of the electrode layer to be structured which is or may comprise a soft-magnetic layer. Etching during the first phase may be chemical or physical etching. By performing, for example, resistance measurements, it can be determined when the rest layer is reached. Preferably, a rest layer having a thickness of maximally 5 nm is aimed at. During a second phase of the etching process, the rest layer is removed by way of physical etching without the other electrode layer being attacked. This surprising effect is achieved in that the particles used during physical etching have a motion energy which is lower than the sputtering threshold of the barrier layer and can therefore not pass through the barrier layer. The physical etching process used is thus a selective etching process. The steps of the method mentioned above do not cause any detrimental effect on the non-structured electrode layer; particularly there is no detrimental influence of the magnetical properties of this electrode layer. If the last-mentioned layer is formed from or also from a soft-magnetic material, this layer is particularly suitable for use as a flux-guiding layer.

An embodiment of the method according to the invention is characterized in that particles are used which have a mass which is heavier than the mass of a metallic element of the magnetic material of the rest layer. In this case, it is assumed that the mass of the elements of the non-magnetic material, generally an oxide or a nitride, of the barrier layer is lighter than the mass of said metallic element. The measure mentioned above positively contributes to the selectivity of the method, in which the selectivity of etching the magnetic material is higher with respect to the non-magnetic material as the charged particles have a heavier mass.

An embodiment of the method according to the invention is characterized in that the electrode layer to be structured is built up from, consecutively, a basic layer and a layer structure comprising at least a further layer for magnetic pinning of the basic layer. The

basic layer may be a ferromagnetic layer, for example, of an NiFe alloy or a Co alloy, particularly a Co-Fe alloy, while the pinning layer structure may comprise one of the following possibilities: an anti-ferromagnetic layer of, for example, an FeMn alloy or an IrMn alloy; a hard-magnetic ferromagnetic layer of, for example, a Co alloy; an artificial anti-ferromagnetic structure comprising two anti-parallel magnetic layers separated by a metallic intermediate layer. Such a structure may be coupled to an anti-ferromagnetic layer of, for example, an FeMn alloy. If such an electrode layer to be structured is formed, it is preferred to selectively etch the layer structure, particularly selectively chemically etch this structure initially, i.e. before the basic layer is structured, until the basic layer is reached. By making partly use of said selective etching, the structuring process in accordance with the method according to the invention can be performed within a shorter period of time. Selective chemical etching is a known etching technique.

It is to be noted that the method according to the invention implies a method of structuring a magnetic electrode layer of a semi-manufactured product of a magnetic tunnel junction device, in which the semi-manufactured product comprises an assembly of said electrode layer, a barrier layer and a further magnetic electrode layer. In the last-mentioned method, the structuring of the relevant layer does not influence the magnetical properties of the other magnetic electrode layer of the magnetic tunnel junction device, at least not in a detrimental sense. The special aspect of this method is that etching does not take place through the barrier layer. It is thereby ensured that, in spite of layer thickness variations and variations of etching methods, the magnetic electrode layer, which is not to be structured, is not etched. The barrier layer, which is an insulating layer, a layer having a low electrical conductance, or a dielectric layer, is usually only approximately 1 nm thick.

The magnetic tunnel junction device according to the invention, manufactured by means of the method according to the invention, has a magnetic electrode layer structured by means of the last-mentioned method and another magnetic electrode layer which may be or may comprise a soft-magnetic layer, which layer is usable as a flux guide. Such a soft-magnetic layer may be formed from, for example, an NiFe alloy or a Co alloy such as a Co-Fe alloy. The soft-magnetic layer may also be built up from a number of sub-layers.

The magnetic field sensor according to the invention is provided with the magnetic tunnel junction device according to the invention. The magnetic tunnel junction device forms one or the transducing element of the magnetic field sensor according to the invention. This sensor may be used, inter alia, as a magnetic head for decoding magnetic flux originating from a magnetic information medium such as a magnetic tape or a magnetic disc;

as a sensor in compasses for detecting the earth's magnetic field; as a sensor for detecting, for example, a position, an angle, or a velocity, for example, in automotive uses; as a field sensor in medical scanners; and as a current detector. Also the magnetic memory, particularly a MRAM, according to the invention is provided with the magnetic tunnel junction device according to the invention.

With regard to the claims, it is to be noted that various combinations of the embodiments mentioned in the dependent claims are possible.

These and other aspects of the invention are apparent from and will be elucidated with reference to the embodiments described hereinafter.

In the drawings:

Fig. 1A shows diagrammatically a first intermediate product obtained from an embodiment of the method according to the invention;

Fig. 1B shows diagrammatically a second intermediate product obtained from said embodiment of the method according to the invention,

Fig. 1C shows diagrammatically a third intermediate product obtained from the embodiment of the method according to the invention,

Fig. 1D shows diagrammatically a fourth intermediate product according to the invention,

Fig. 1E shows diagrammatically an embodiment of the magnetic tunnel junction device according to the invention, made in accordance with the described embodiment of the method according to the invention, and

Fig. 2 shows an embodiment of the magnetic field sensor according to the invention.

Fig. 1A shows a stack 1 of layers which comprises, in this example, a first magnetic electrode layer 3 of a soft-magnetic material, such as an NiFe alloy, an insulating, poorly conducting or dielectric layer 5, in this document also referred to as barrier layer, of, for example Al_2O_3 , a second magnetic electrode layer 7 built up in this example of a basic layer 7a of a soft-magnetic material, in this example an NiFe alloy, and a layer structure 7b comprising at least a further layer of an anti-ferromagnetic material such as an FeMn alloy. Alternatively, a hard-magnetic layer may be used as a second magnetic layer for the layer structure comprising the basic layer 7a and the layer structure 7b.

During the method according to the invention, a shielding layer 9 of, for example, a photoresist, see Fig. 1B, is provided on the stack 1 shown. Subsequently, etching processes are used, in which the layer structure 7b is first etched selectively, particularly etched chemically, until the basic layer 7a is reached; see Fig. 1C. Subsequently, the basic layer 7a is etched, particularly etched physically, until a rest layer 7r of soft-magnetic material remains; see Fig. 1D. Alternatively, instead of two etching processes, it may be sufficient to use physical etching only. Physical etching such as sputter etching is preferably also used if the second electrode layer 7 is a hard-magnetic layer. During physical etching, resistance measurements are performed continuously or occasionally, possibly during a short interruption of the etching process, so as to determine when the desired rest layer 7r is reached.

The rest layer 7r obtained in one of the methods described above preferably has a thickness of 5 nm maximum. During the method according to the invention, the rest layer 7r is removed by physical etching, in this example sputter etching, in which charged particles, particularly ions, have a motion energy which is between the sputtering threshold of the NiFe alloy used and the sputtering threshold of Al_2O_3 . The sputtering threshold of the NiFe alloy is approximately 20 eV; the sputtering threshold of Al_2O_3 is approximately 40 eV. In this embodiment, the rest layer 7r is preferably bombarded with Kr or Xe ions which ions have a mass which is heavier than the mass of the metals Ni and Fe, which mass is in its turn heavier than the mass of Al and O. After removal of the rest layer 7r, a protective layer 11 may be formed by depositing an insulating material such as SiO_2 or Al_2O_3 . The shielding layer 9 may be removed.

The magnetic field sensor according to the invention, shown in Fig. 2, comprises a magnetic tunnel junction device 20 of the type shown in Fig. 1E. In this embodiment, the sensor also comprises a magnetic yoke 22 which has an interruption 22a which is bridged and is in magnetic contact with the tunnel junction device 20. The magnetic yoke 22 is formed from a soft-magnetic material such as an NiFe alloy. The sensor has a sensor face 24 adjacent to a non-magnetic transducing gap 26. The interruption 22a and the gap 26 are formed by insulating layers of, for example SiO_2 or Al_2O_3 .

It is to be noted that the invention is not limited to the embodiments shown. For example, variants of the several steps of the method are possible within the scope of the invention. Furthermore, the sensor shown may be formed as a magnetic head for scanning a magnetic recording medium. Such a construction may form part of a combined read/write head. The magnetic tunnel junction device obtained in accordance with the method of the invention may also form part of a magnetic memory.

CLAIMS:

1. A method of manufacturing a magnetic tunnel junction device, in which a stack comprising two electrode layers, comprising a magnetic material, and a barrier layer extending in between, comprising a non-magnetic material, is formed, characterized in that one of the electrode layers is structured by means of etching, in which, during etching, a part of the relevant layer is made thinner by removing material until a rest layer remains, whereafter said rest layer is removed by means of physical etching, in which at least substantially particles have a motion energy which is between the sputtering threshold of the magnetic material of the rest layer and the sputtering threshold of the non-magnetic material of the barrier layer.

2. A method as claimed in claim 1, characterized in that particles are used which have a mass which is heavier than the mass of a metallic element of the magnetic material of the rest layer.

3. A method as claimed in claim 1, characterized in that the electrode layer to be structured is built up from, consecutively, a basic layer and a layer structure comprising at least a further layer for magnetic pinning of the basic layer.

4. A method as claimed in claim 3, characterized in that, prior to structuring the basic layer, the layer structure is chemically etched until the basic layer is reached.

5. A magnetic tunnel junction device obtained by means of the method as claimed in any one of the preceding claims.

6. A magnetic tunnel junction device as claimed in claim 5, in which the layer other than the structured electrode layer comprises a soft-magnetic layer which is usable as a flux guide.

7. A magnetic field sensor provided with the magnetic tunnel junction device as claimed in claim 5.

8. A magnetic field sensor provided with the magnetic tunnel junction device as claimed in claim 6 and provided with a magnetic yoke which is in magnetic contact with the soft-magnetic layer of the magnetic tunnel junction device.

5

9. A magnetic memory provided with the magnetic tunnel junction device as claimed in claim 5.

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"0322ED" 8E878760

ABSTRACT:

A method of manufacturing a magnetic tunnel junction device, in which a stack (1) comprising two electrode layers (3, 7) and a barrier layer (5) extending in between is formed. One of the electrode layers is structured by means of etching, in which, during etching, a part of this layer is made thinner by removing material until a rest layer (7r) remains. This rest layer is subsequently removed by means of physical etching, in which at least substantially charged particles have a motion energy which is between the sputtering threshold of the magnetic material of the rest layer and the sputtering threshold of the non-magnetic material of the barrier layer. In the relevant method, it is prevented that the electrode layer which is not to be structured is detrimentally influenced during structuring of the other electrode layer.

Fig. 1E

1/2

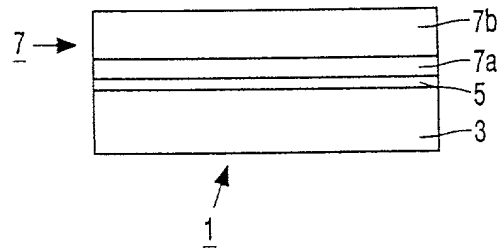


FIG. 1A

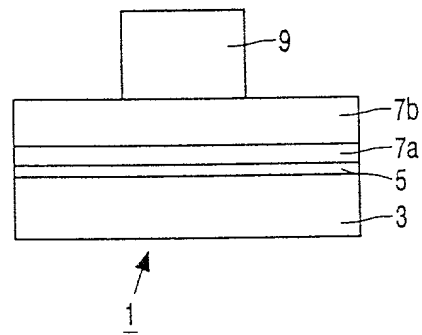


FIG. 1B

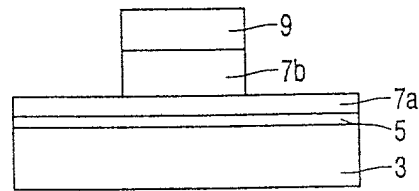


FIG. 1C

2/2

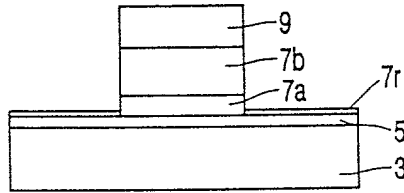


FIG. 1D

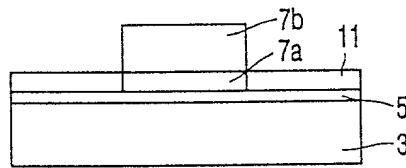


FIG. 1E

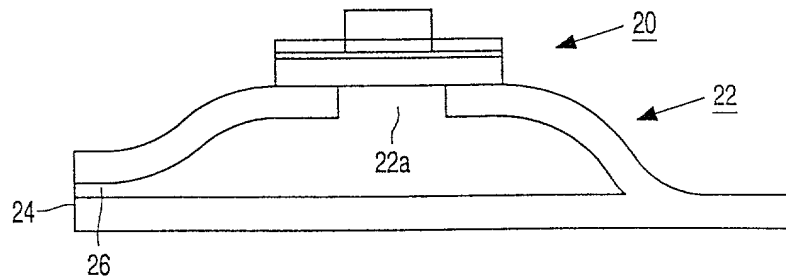


FIG. 2

In re Application of
JOANNES B.A.D. VAN ZON

Atty. Docket

PHN 17,557

Filed: CONCURRENTLY

METHOD OF MANUFACTURING A MAGNETIC TUNNEL JUNCTION DEVICE

Commissioner for Patents, Washington, D.C. 20231

APPOINTMENT OF ASSOCIATES

Sir:

The undersigned Attorney of Record hereby revokes all prior appointments (if any) of Associate Attorney(s) or Agent(s) in the above-captioned case and appoints:

MICHAEL E. BELK

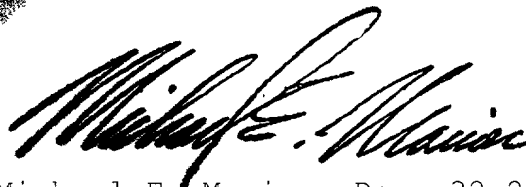
Registration 33,357

3

c/o U.S. PHILIPS CORPORATION, Intellectual Property Department, 580 White Plains Road, Tarrytown, New York 10591, his Associate Attorney(s)/Agent(s) with all the usual powers to prosecute the above-identified application and any division or continuation thereof, to make alterations and amendments therein, and to transact all business in the Patent and Trademark Office connected therewith.

ALL CORRESPONDENCE CONCERNING THIS APPLICATION AND THE LETTERS PATENT WHEN GRANTED SHOULD BE ADDRESSED TO THE UNDERSIGNED ATTORNEY OF RECORD.

Respectfully,



Michael E. Marion, Reg. 32,266
Attorney of Record

Dated at Tarrytown, New York
on 21 March, 2001.

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled: **"Method of manufacturing a magnetic tunnel junction device"**
the specification of which (check only one item below):

☐ is attached hereto.

☐ was filed as United States application

Serial No _____

on _____

and was amended

on _____

☒ was filed as PCT international application

Number PCT/EP00/06817

on 17 July 2000

and was amended under PCT Article 19

on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, § 1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate or of any PCT international application(s) designating at least one country other than the United States of America listed below and have identified below any foreign application(s) for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America filed by me on the same subject matter having a filing date before that of the application(s) of which priority is claimed:

PRIOR FOREIGN/PCT APPLICATION(S) AND ANY PRIORITY CLAIMS UNDER 35 U.S.C. 119:

COUNTRY	APPLICATION NUMBER	DATE OF FILING DAY, MONTH, YEAR	PRIORITY CLAIMED UNDER 35 USC 119
Europe	99202417.4	22 July 1999	YES

Combined Declaration For Patent Application and Power of Attorney (Continued)
(includes Reference to PCT International Applications)

Attorneys Docket Number
PHN 17.557 US

POWER OF ATTORNEY: As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith. (List name and registration number)

Algy Tamoshunas Reg. No. 27,677
Jack E. Haken, Reg. No. 26,902

Direct Telephone Calls to:
(name and telephone number)
(914)332-0222

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	POST OFFICE ADDRESS	POST OFFICE ADDRESS	CITY	STATE & ZIP CODE/COUNTRY
203	FULL NAME OF INVENTOR	FAMILY NAME	FIRST GIVEN NAME	SECOND GIVEN NAME
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	POST OFFICE ADDRESS	POST OFFICE ADDRESS	CITY	STATE & ZIP CODE/COUNTRY
204	FULL NAME OF INVENTOR	FAMILY NAME	FIRST GIVEN NAME	SECOND GIVEN NAME
	RESIDENCE & CITIZENSHIP	CITY	STATE OR FOREIGN COUNTRY	COUNTRY OF CITIZENSHIP
	POST OFFICE ADDRESS	POST OFFICE ADDRESS	CITY	STATE & ZIP CODE/COUNTRY
205	FULL NAME OF INVENTOR	FAMILY NAME	FIRST GIVEN NAME	SECOND GIVEN NAME
	RESIDENCE & CITIZENSHIP	CITY	STATE OR FOREIGN COUNTRY	COUNTRY OF CITIZENSHIP
	POST OFFICE ADDRESS	POST OFFICE ADDRESS	CITY	STATE & ZIP CODE/COUNTRY

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true: and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

SIGNATURE OF INVENTOR 201 CITY	SIGNATURE OF INVENTOR 202	SIGNATURE OF INVENTOR 203
DATE 15 February 2001	DATE	DATE
SIGNATURE OF INVENTOR 204	SIGNATURE OF INVENTOR 205	
DATE	DATE	

U.S. DEPARTMENT OF COMMERCE- Patent and Trademarks Office

(July 1994)